

Excellent Integrated System Limited

Stocking Distributor

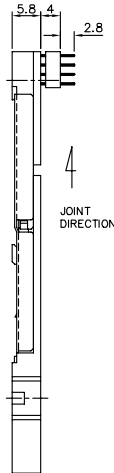
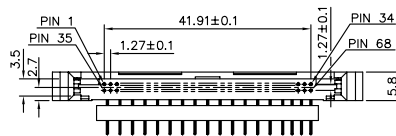
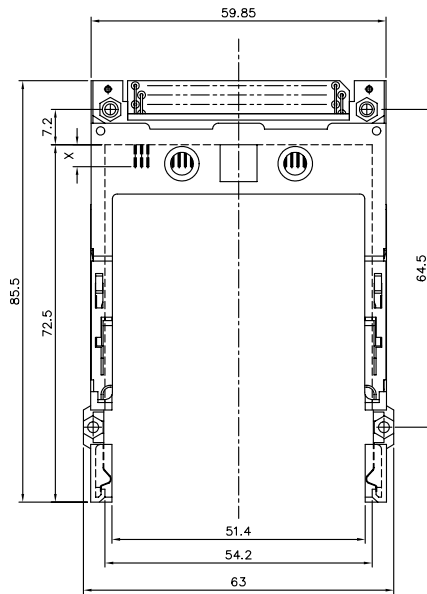
Click to view price, real time Inventory, Delivery & Lifecycle Information:

[FCI](#)
[74500-000LF](#)

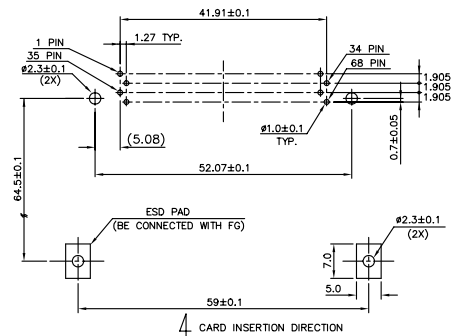
For any questions, you can email us directly:

sales@integrated-circuit.com

PRODUCT NO.
74500-040
74500-040LF

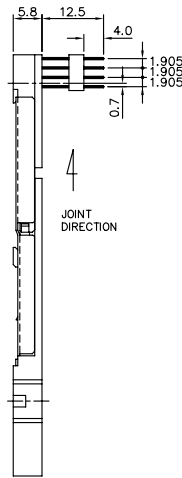
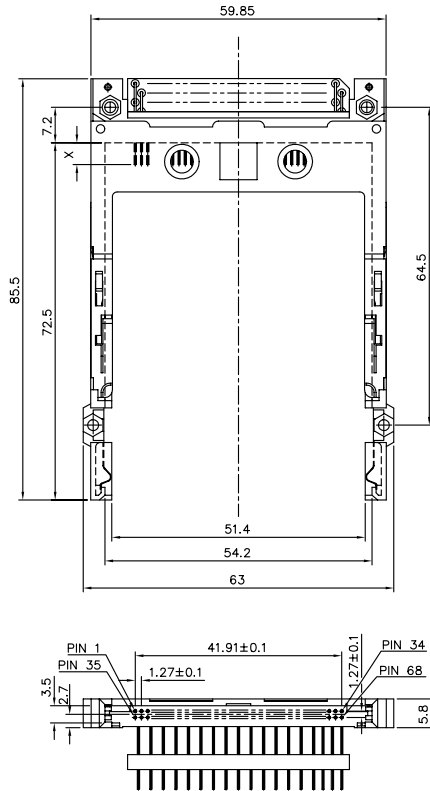


- NOTES:
- EJECT FORCE : 3.5 Kg MAX.
 - EJECT TRAVEL: 8.0mm
 - MATERIAL:
 - HEADER ASS'Y :
 - HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
 - PIN : COPPER ALLOY
 - EJECT MECHANISM ASS'Y :
 - HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
 - PLATE : STAINLESS
 - EMI CONTACT: PHOSPHOR BRONZE
 - FINISH (PIN)
 - UNDER PLATING : 0.5µm MIN. NI
 - CONTACT AREA : 0.076 µm MIN. GOLD
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb (FOR TIN LEAD OPTION)
 - : 2.5µm MIN. PURE TIN (FOR LEAD FREE OPTION)
 - | DIM"x" | 4.25±0.1 | 3.5±0.1 | 5.0±0.1 |
|------------|----------|---------|------------------|
| PIN NUMBER | OTHERS | 36,67 | 1,17,34,35,51,68 |
 - IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER 260°C APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
 - IF LEAD FREE P/N, THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
 - LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
 - PRODUCT SPEC: 110-263



mat'l. code	surface	tolerance	projection	product family
	ISO1302	ISO406 ISO1101		PCMCIA
l'tecn n'dr	date	tolerances unless otherwise specified	angle	title
A	T70405 WL 0923/97	0.X±0.3	MM	EJECTOR HEADER ASS'Y
B	T80096 WL 02/17/98	0.XX±0.13	scale: 1.6:1	68POS. R/A TYP 1/2/3
C	T03-0326 WL 08/14/03	0'±2'		
D	N05-0127 WB 05/11/05	dr WENDY.CHEN 07/30/97		dwg no sheet 1 of 2 size
E	BX-N-007947 ZK 11/01/11	engr JOSEPH HSIA 07/30/97		74500 A4
F	BX-N-011428 ZK 04/07/12	chr JOSEPH HSIA 07/30/97		type Product Customer Drawing
		appd JENN TSAO 07/30/97		
sheet	revision	F		
index	sheet	1 2		

PRODUCT NO.
74500-000
74500-000LF



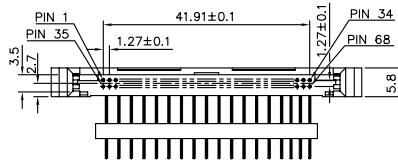
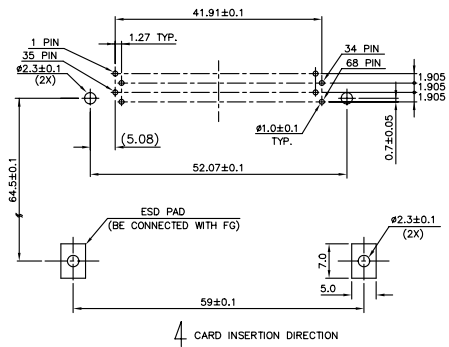
NOTES:

1. MATERIAL
 - 1.1 HEADER ASS'Y : HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK PIN: COPPER ALLOY
 - 1.2 EJECT MECHANISM ASS'Y : HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK PLATE: STAINLESS EM CONTACT: PHOSPHOR BRONZE
2. FINISH (PIN)

UNDER PLATING : 0.5μm MIN. NI
CONTACT AREA : 0.076 μm MIN. GOLD

SOLDER TAIL : 2.5μm MIN. Sn-Pb (FOR TIN LEAD OPTION)
: 2.5μm MIN. PURE TIN (FOR LEAD FREE OPTION)
3.

DIM"x"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
4. IF LEAD FREE P/N THE HOUSING WILL WITHSTAND EXPOSURE TO PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER 260°C APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
5. IF LEAD FREE P/N THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
6. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
7. PRODUCT APEC: 110-263



mat'l. code	surface	tolerance	projection	product family
ISD1302	✓	ISD406 ISD1101	MM	PCMCIA
l'tecn n'dr date	tolerances unless otherwise specified	angle	scale	title
F	0.X±0.3	0°±2'	scale 1.6:1	EJECTOR HEADER ASS'Y
	0.XX±0.13			68POS. R/A TYP 1/2/3
	0.XXX±0.05			dwg no
dr WENDY CHEN 07/30/97				74500
engr JOSEPH HSIA 07/30/97				sheet 2 of 2
chr JOSEPH HSIA 07/30/97				A4
appd JENN TSAO 07/30/97				type Product Customer Drawing
sheet	revision			
index	sheet			